



FEATURES

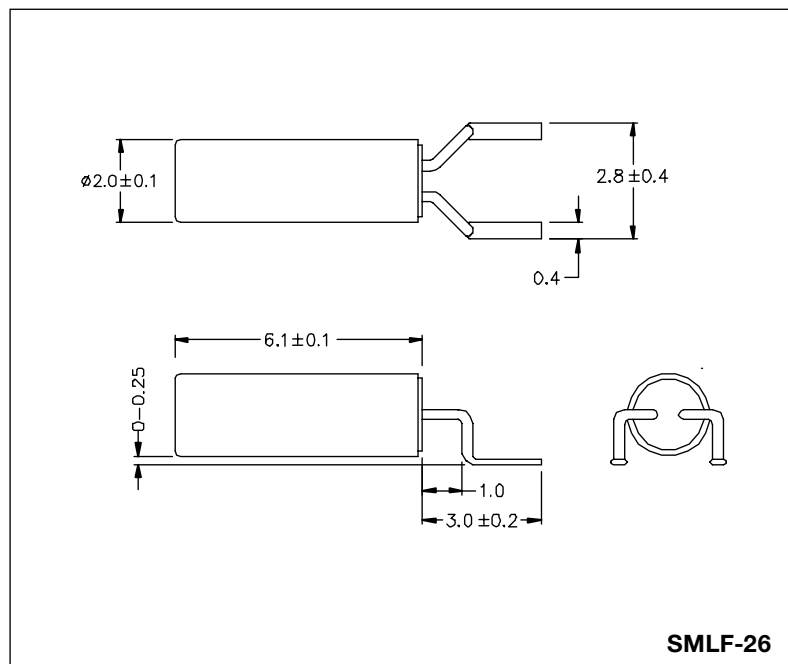
- Small Size
- Surface Mount
- Pick and Place Assembly



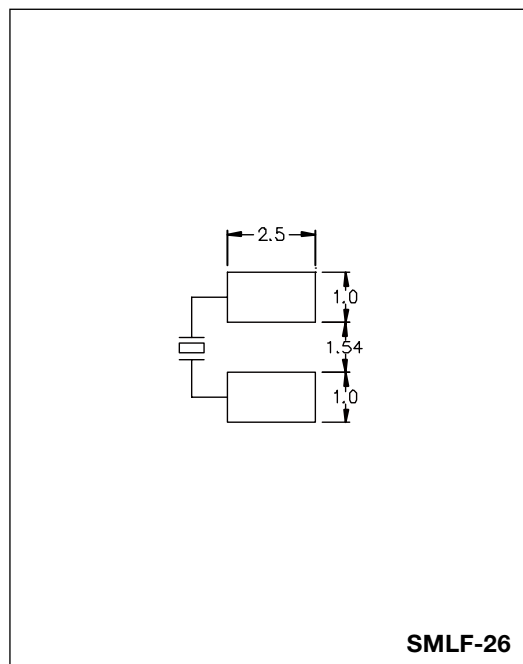
Parameters		Specifications
Nominal Frequency 標稱頻率	f_0	Standard : 32.768KHz Optional : 30KHz ~ 200KHz
Frequency Tolerance, Ta=25°C ± 3°C 常溫頻率偏差	$\Delta f/f$	±20ppm
Load Capacitance 負載電容	C_L	12.5pF or customer specify
Temperature Coefficient 溫度系數	$\Delta f/f$	-0.034±0.006ppm/°C ²
Operating Temperature Range 工作溫度範圍	T _{OPR}	-20°C ~ +70°C
Storage Temperature Range 儲存溫度範圍	T _{STG}	-55°C ~ +125°C
Drive Level 激勵功率	DL	0.001mW Max.
Series Resistance (ESR) 串聯諧振阻抗	R ₁	50KΩ Max.
Insulation Resistance 絕緣阻抗	IR	500MΩ Min.
Aging 老化率	Δf_A	±5ppm/Year Max.

Please consult our sales representatives for other specifications.
如對其他規格查詢，請與我司銷售人員聯繫

DIMENSION (mm)



SOLDERING PATTERN (mm)



Handling instructions.

- 1 Soldering on the body of the enclosure should be strictly avoided as it might damage the crystal.
Rubber adhesive is recommended to hold the crystal on the PCB.
直接焊接於晶體外殼上可引致內部結構受損。如需固定晶體外殼，建議使用工業橡膠。
- 2 Maximum reflow soldering temperature at +235°C for 5 seconds.
迴流焊最高溫度為 +235°C，維持不多於 5 秒。

All specifications are subject to change without prior notice.
本公司保留修改規格的權利。

